Revision. 2

Junction FETs

DSK5J01×0L

Panasonic

DSK5J01×0L

Silicon N-channel Junciton FET

For low frequency amplification / For pyroelctric sensor DSK2J01 in SMini3 type package

■ Features

- High gate-drain Voltage(Source open)VGDO
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: B6

■ Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

Unit: mm

2. 0

0. 3

0. 13

(0. 65)(0. 65)

1. 3

1. Source
2. Drain
3. Gate

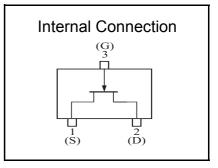
Panasonic SMini3-F2-B

JEITA SC-85

Code —

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Gate-drain voltage (Source short)	VGDS	-55	V
Drain current	ID	30	mA
Gate current	IG	10	mA
Power dissipation	PD	150	mW
Channel temperature	Tch	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Gate-drain voltage (Source short)	VGDS	IG = -100 μA, VDS = 0	-55			V
Drain current *1	IDSS	VDS = 10 V , VGS = 0	1.0		12.0	mA
Gate-source cutoff current	IGSS	VGS = -30 V, VDS = 0			-10	nA
Gate-source cutoff voltage	VGSC	VDS = 10 V, ID = 10 μA			-5	V
Forward transfer admittance	Yfs	VDS = 10 V, ID = 5 mA, f = 1 kHz	2.5	7.5		mS
Small-signal short-circuit input capacitance	Ciss	VDS = 10 V, VGS = 0, f = 1 MHz		6.0		pF
Small-signal reverse transfer capacitance	Crss			2.5		pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

*1 Rank classification

Rank P Q R			
	R		
IDSS (mA) 1.0 to 3.0 2.0 to 6.5 5.0 to 1	12.0		
Marking symbol B6P B6Q B6R	B6R		

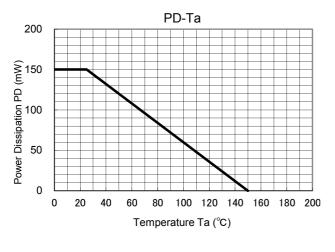
Page 1 of 3

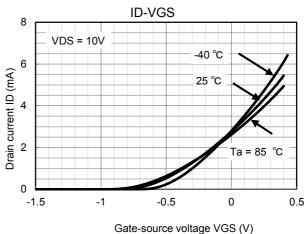
Established: 2010-10-26 Revised: 2014-03-25

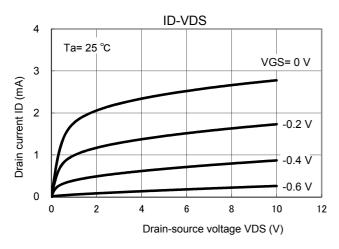
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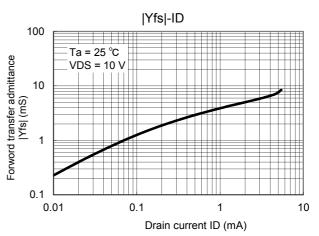
Junction FETs DSK5J01×0L

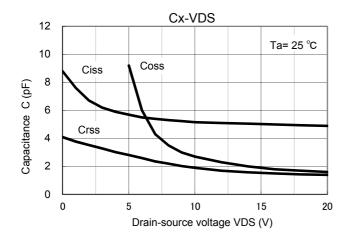
Technical Data (reference)











Page 2 of 3

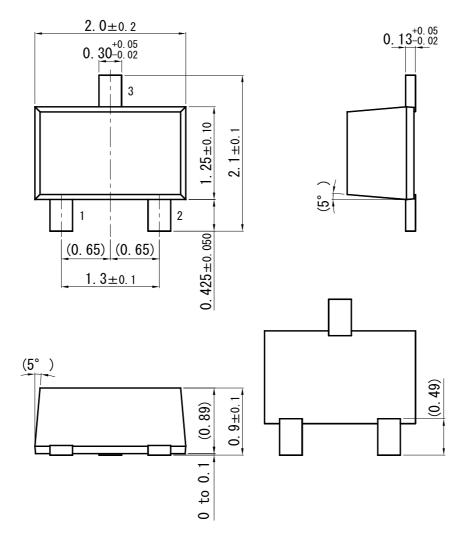
Junction FETs

DSK5J01×0L

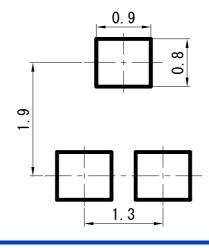
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SMini3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



Page 3 of 3

Established: 2010-10-26 Revised: 2014-03-25

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